CLAIMS

1. A low application temperature hot melt adhesive that passes the IoPP Heat Stress test at a temperature of at least about 140°F.

2. The adhesive of claim 1 that passes the IoPP Heat Stress test at a temperature of at least about 150°F.

3. A hot melt adhesive comprising a mixture of ethylene copolymers having a melt index of 750 grams/10 minutes or greater, a Fischer-Tropsch wax and a modified rosin ester tackifier having a minimum softening point of about 110°C.

4. The adhesive of claim 3 wherein the tackifier is a maleic anhydride modified Chinese gum rosin.

5. The adhesive of claim 3 comprising at least one ethylene n-butyl acrylate copolymer having a melt index of greater than about 900 grams/minute.

6. The adhesive of claim 5 comprising an ethylene vinyl acetate copolymer having a melt index of greater than about 900 grams/minute

7. The adhesive of claim 6 comprising 20 to about 30 wt % EnBA copolymer containing from about 30 to about 40 wt % of n-butyl acrylate, from about 5 to about 15 wt % EVA copolymer containing from about 20 to about 35 wt % of vinyl acetate, from about from about 20 to about 40 wt % of a Fischer-Tropsch wax having a melting point of from about 60 to about 80°C, and from about 20 to about 45 wt % of a modified rosin ester having a minimum softening point of about 110°C.

8. The adhesive of claim 7 comprising about 25 wt % of an EnBA copolymer containing 33 wt % n-butyl acrylate and having a MI of about 750 or greater, about 10 wt %

of an EVA copolymer containing about 28 wt % vinyl acetate and having MI of about 750 or greater, 30% of a Fischer-Tropsch wax having a melting point of about 71°C, and 35 % of a maleic anhydride modified Chinese gum rosin.

9. An article of manufacture comprising the adhesive of claim 3.

10. The article of claim 9 wherein the adhesive comprises 20 to about 30 wt % EnBA copolymer containing from about 30 to about 40 wt % of n-butyl acrylate, from about 5 to about 15 wt % EVA copolymer containing from about 20 to about 35 wt % of vinyl acetate, from about from about 20 to about 40 wt % of a Fischer-Tropsch wax having a melting point of from about 60 to about 80°C, and from about 20 to about 45 wt % of a modified rosin ester having a minimum softening point of about 110°C.

11. The article of claim 10 which is a carton, case, tray, bag or book.

12. A method of sealing and/or forming a case, carton, tray, bag or book comprising applying the hot melt adhesive of claim 3 to seal and/or form the case, carton, tray, bag or book.

13. A packaged article contained within a carton, case, tray or bag, wherein the carton, case, tray or bag comprises the adhesive of claim 3.

14. The packaged article of claim 13 which is a packaged food article.

15. A process for bonding a substrate to a similar or dissimilar substrate comprising applying to at least one substrate a molten hot melt adhesive composition comprising 20 to about 30 wt % EnBA copolymer containing from about 30 to about 40 wt % of n-butyl acrylate, from about 5 to about 15 wt % EVA copolymer containing from about 20 to about 35 wt % of vinyl acetate, from about from about 20 to about 40 wt % of a Fischer-Tropsch

wax having a melting point of from about 60 to about 80°C, and from about 20 to about 45 wt % of a modified rosin ester having a minimum softening point of about 110°C.

16. The process of claim 15 wherein the adhesive is applied to said at least one substrate at a temperature of from about 100 to about 150°C.